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(12) **United States Design Patent**
Bullen et al.

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(54) **HEADPHONES**

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(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **14-01**

(52) **U.S. Cl.**
USPC **D14/205**

(58) **Field of Classification Search**
USPC D14/205, 206, 188, 192, 372; D29/112;
2/209; 181/129, 130, 135; 379/430, 431;
381/380, 381, 74, 374, 371, 370; 345/7,
345/8; 455/90.3, 575.1, 569.1
CPC H04R 25/00; H04R 1/1066; H04R 1/1016;
H04R 5/033; H04R 5/0335
See application file for complete search history.

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(57) **CLAIM**

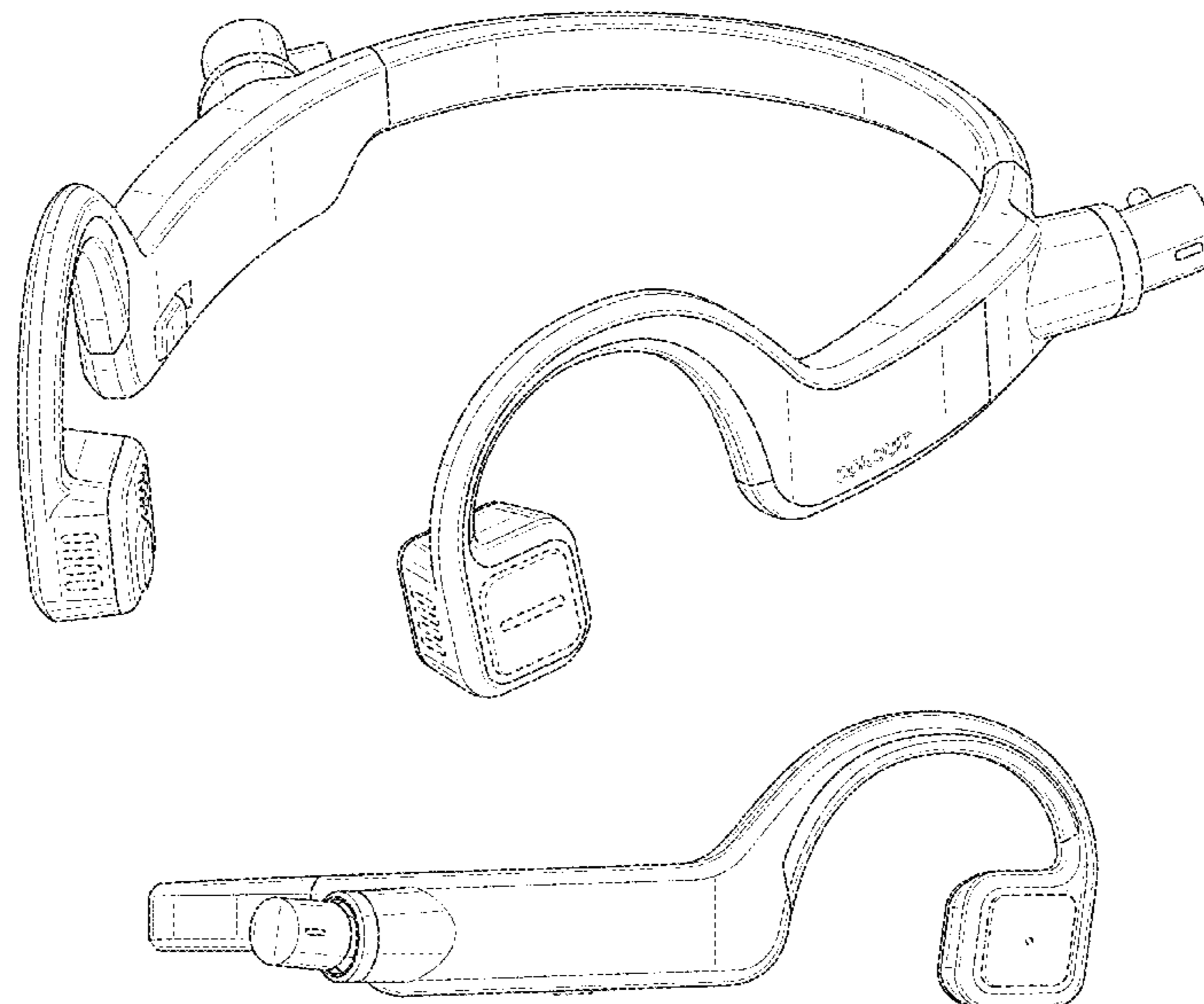
The ornamental design for headphones, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of an embodiment of headphones;
 FIG. 2 is a front view of an embodiment of the headphones of FIG. 1;
 FIG. 3 is a rear view of an embodiment of the headphones of FIG. 1;
 FIG. 4 is a left side view of an embodiment of the headphones of FIG. 1;
 FIG. 5 is a right side view of an embodiment of the headphones of FIG. 1;
 FIG. 6 is a top view of an embodiment of the headphones of FIG. 1; and,
 FIG. 7 is a bottom view of an embodiment of the headphones of FIG. 1.

The broken lines in the drawings show unclaimed subject matter only and form no part of the claimed design

1 Claim, 5 Drawing Sheets



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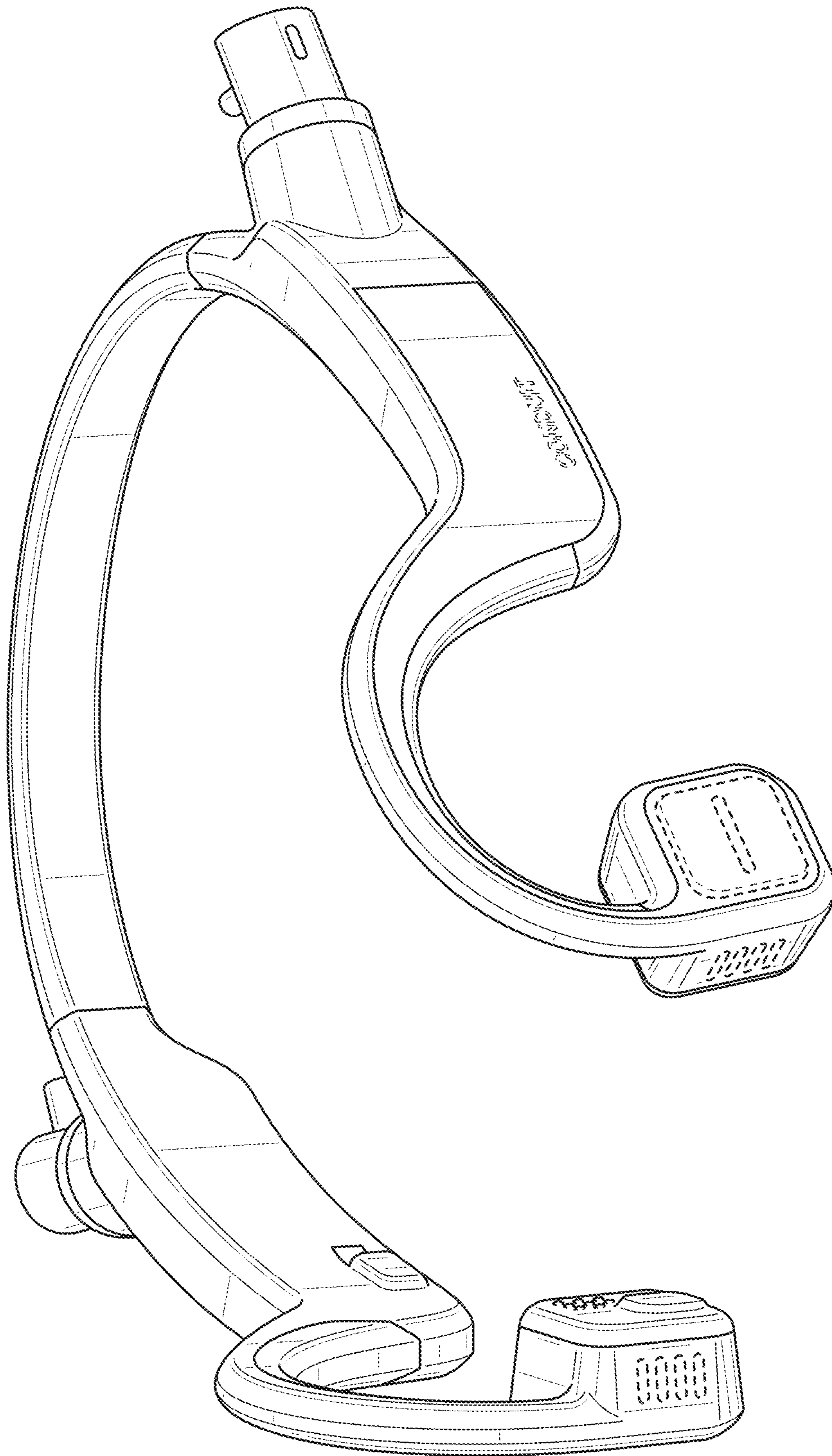


FIG. 1

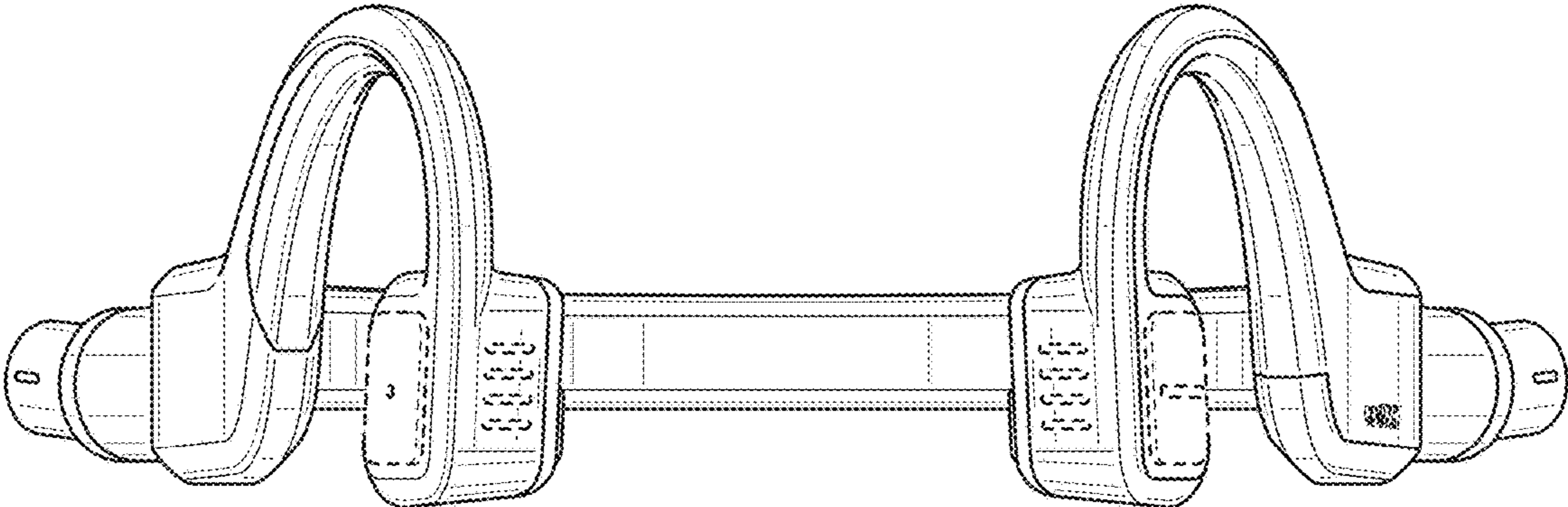


FIG. 2

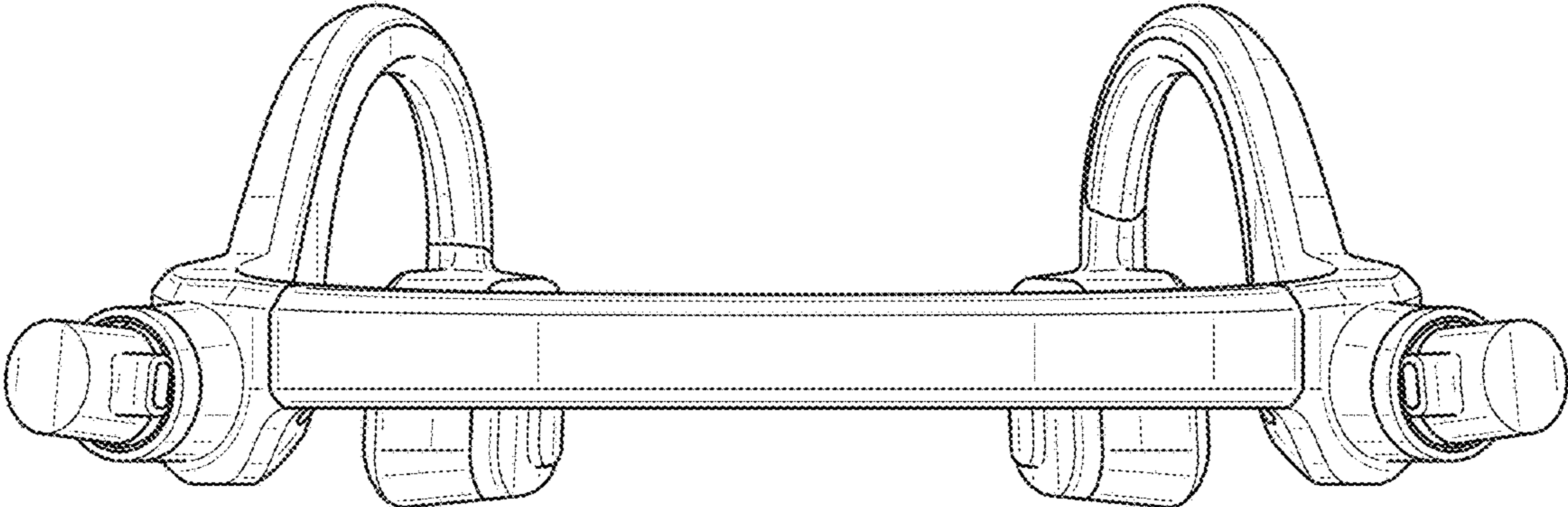


FIG. 3

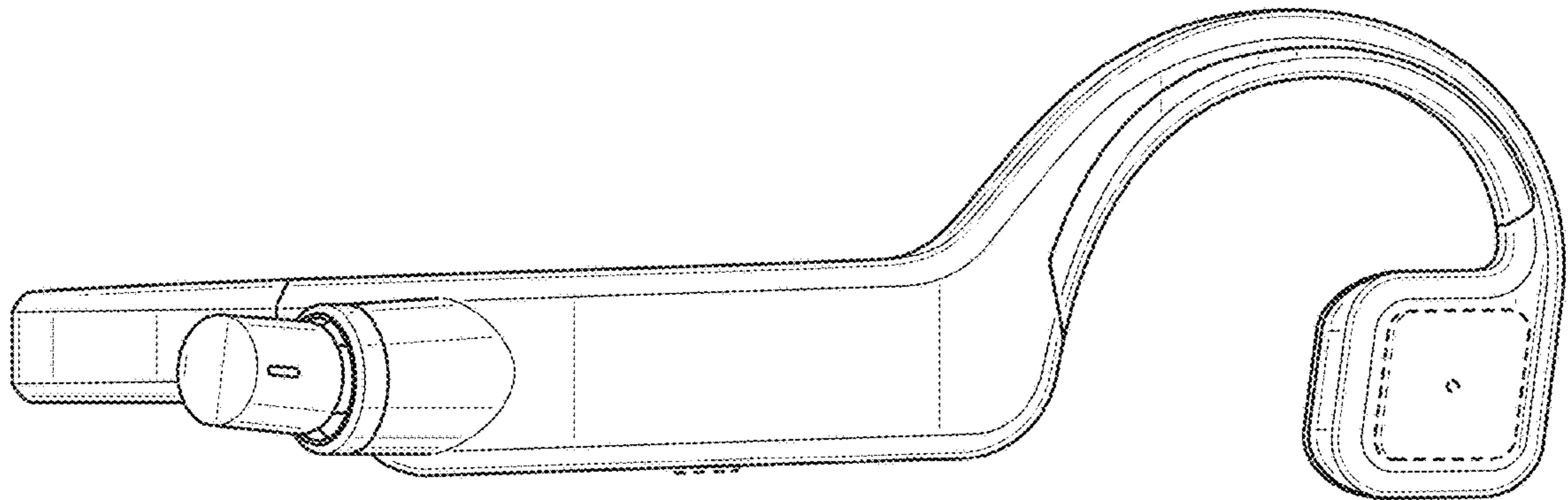


FIG. 4

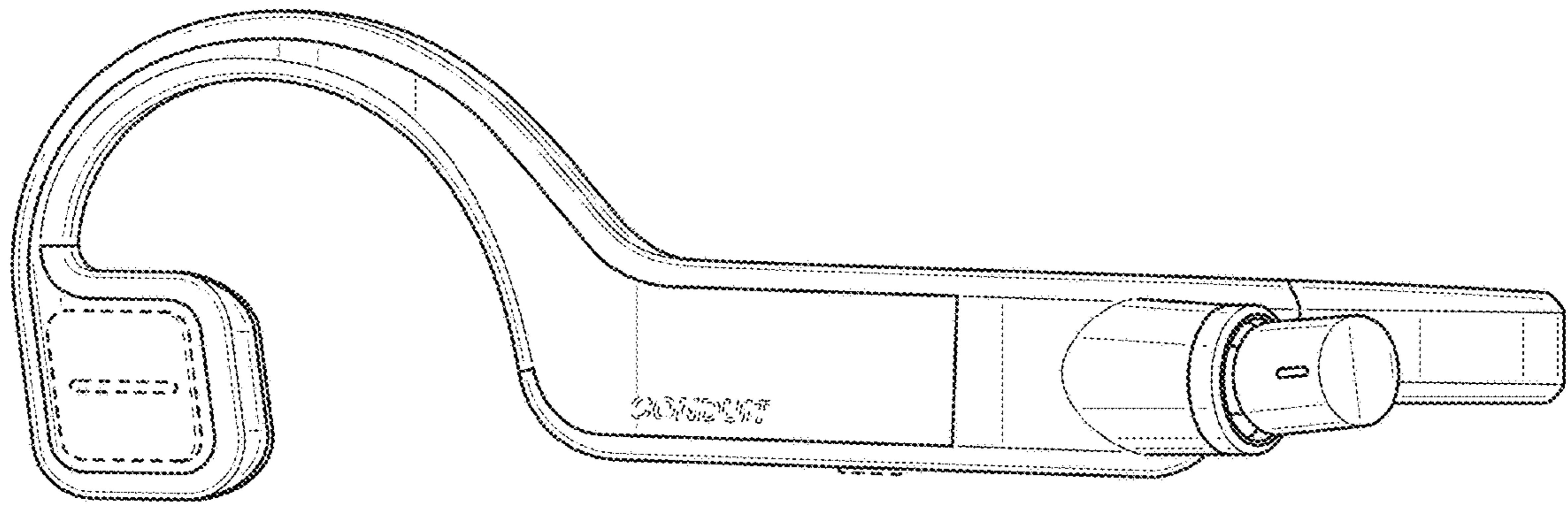


FIG. 5

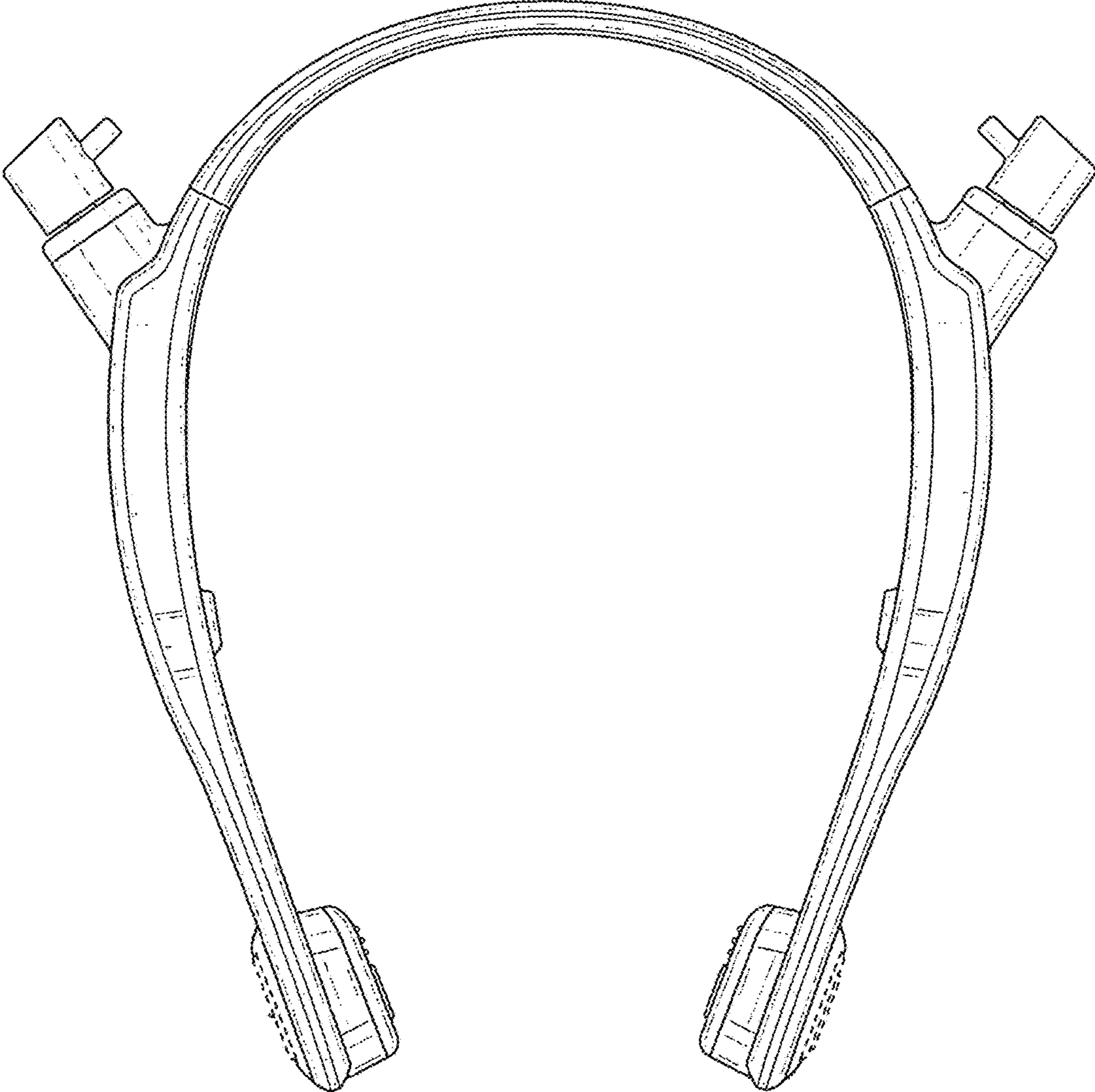


FIG. 6

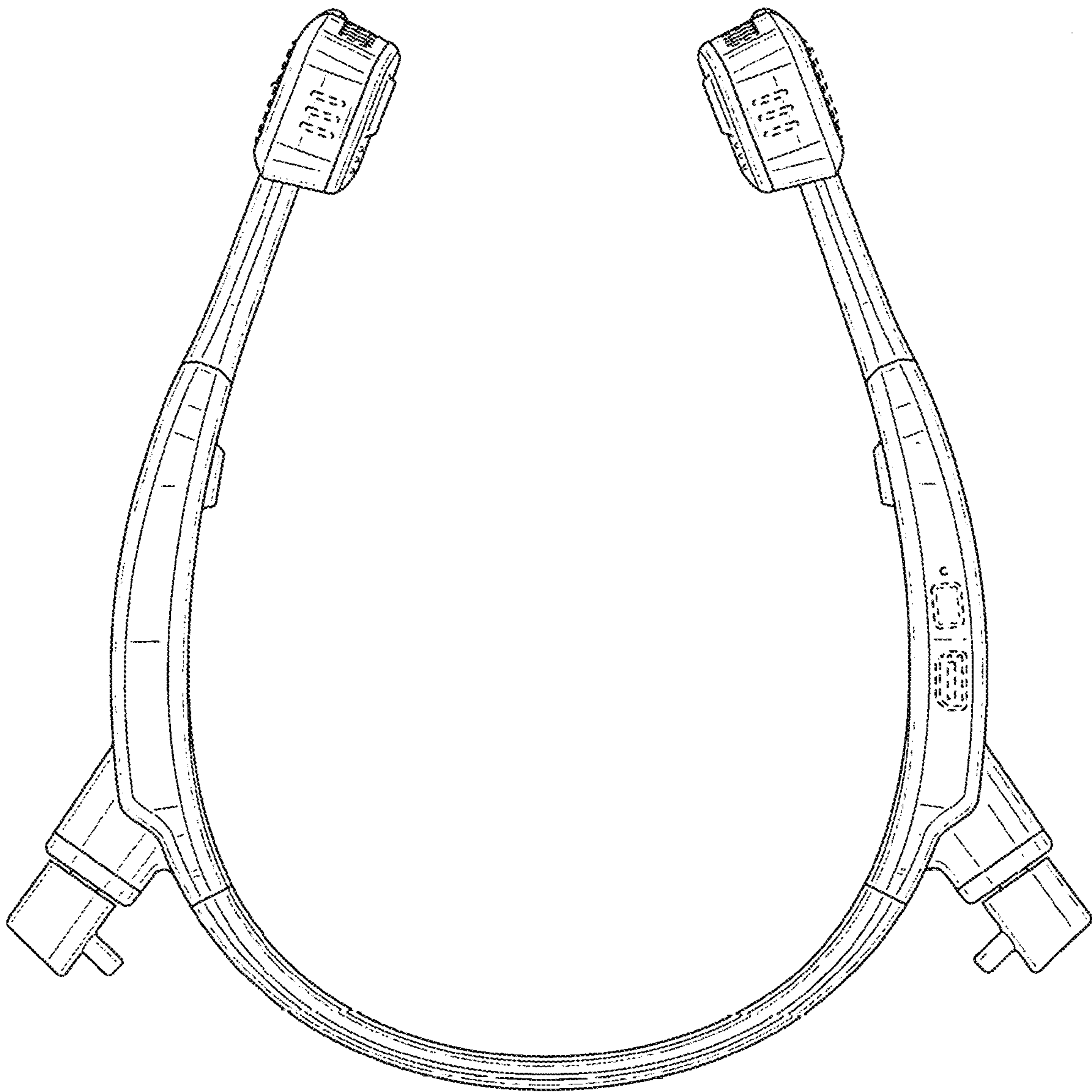


FIG. 7